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Signature

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Box Assignments Washington, D.C. 20231

> PATENT REEL: 011844 FRAME: 0734

Date

For good and valuable consideration, of which I acknowledge receipt, I, as a below-named assignor, sell and assign

		er the laws of the
rlands, whose business add	lress is Groenewoudseweg 1, 5621 BA Ein	dhoven, the
sors and assigns, the applic	cation for a United States Patent for the im-	provements in a
turing a semiconductor d	evice" invented by us, which application:	
ently herewith		
e/us on		
olication No	,filed,	
nsions thereof, and authori d improvements or resultin Il right so to do, and agree respecting said improvement continuing and reissue app	ze and request the Commissioner of Patent ig therefrom to said Assignee as assignee of that I will communicate to said Assignee of ents and testify in any legal proceeding, sig- dications, make all rightful oaths and gener	s and Trademarks to f the entire interest and or its representatives on all lawful papers, ally do everything
(sign name here) (print name here)	Waiterus Theodorus Franciscus	, Assignor
	Maria DE LAAT	
	turing a semiconductor dently herewith elus on filed f	e/us on

Petrus Maria MEIJER

(sign name here)
(print name here)

, Assignor

For good and valuable	consideration, of which I a	cknowledge receipt, I, as a below-named as	ssignor, sell and assign	
to Koninklijke Philips I	Electronics N.V. (hereinaf	ter "Assignee") a corporation existing unde	er the laws of the	
Kingdom of the Nether	lands, whose business add	ress is Groenewoudseweg 1, 5621 BA Eind	lhoven, the	
Netherlands, its success	sors and assigns, the applic	eation for a United States Patent for the imp	rovements in a	
"Method of manufact	uring a semiconductor de	evice" invented by us, which application:		
"Method of manufacturing a semiconductor device" invented by us, which application: is executed concurrently herewith was executed by me/us on is Serial No. is Serial No. filed is International Application No. filed filed				
Date	(sign name here) (print name here)	Walterus Theodorus Franciscus Maria DE LAAT	, Assignor	
Date	(sign name here)	Johannes VAN WINGERDEN	, Assignor	
April 18, 2001 Date	(sign name here)	Petrus Maria MEIJER	, Assignor	

RECORDED: 05/24/2001